Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)

Contact Info: ti.com/support

Form/Declaration Type: Distribute - RoHS and IEC 62474 DB

Created on: 06/13/2022

Details for "UC3844NG4"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
UC3844NG4	NIPDAU	Level-NC-NC-NC	TI AGUASCALIENTES	P 8	9.8x6.4x3.9	677.1

*Total Device Mass

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

		<u> </u>		Homogeneous Material Level		Component Level	
Component	Substance	CAS Number	Amount (mg)	Percentage %	ppm	Percentage %	ppm
Bond Wire							
Copper and Its Alloys	Copper	7440-50-8	0.000001	0.000317	3	0	C
Precious Metals	Gold	7440-57-5	0.31555	99.996197	999962	0.046606	466
Precious Metals	Palladium	7440-05-3	0.000002	0.000634	6	0	(
Precious Metals	Silver	7440-22-4	0.000009	0.002852	29	0.000001	(
Sub-Total			0.315562	100	1000000	0.046608	466
Die Attach Adhesive							
Precious Metals	Silver	7440-22-4	0.594634	79.000028	790000	0.087826	878
Thermoplastics	Ероху	85954-11-6	0.158067	20.999972	210000	0.023346	233
Sub-Total			0.752701	100	1000000	0.111173	1112
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	211.481655	97.05	970500	31.235458	312355
Copper and Its Alloys	Iron	7439-89-6	5.66566	2.6	26000	0.836808	8368
Copper and Its Alloys	Phosphorus	7723-14-0	0.326865	0.15	1500	0.048277	483
Zinc and Its Alloys	Zinc	7440-66-6	0.43582	0.2	2000	0.06437	644
Sub-Total			217.91	100	1000000	32.184913	321849
Lead Frame Plating							
Nickel and Its Alloys	Nickel	7440-02-0	0.722912	95.12	951200	0.106773	1068
Precious Metals	Gold	7440-57-5	0.005928	0.78	7800	0.000876	
Precious Metals	Palladium	7440-05-3	0.03116	4.1	41000	0.004602	46
Sub-Total			0.76	100	1000000	0.112251	1123
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	399.922936	88	880000	59.067894	590679
Other Plastics and Rubber	Carbon Black	1333-86-4	1.363374	0.3	3000	0.201368	2014
Other Plastics and Rubber	Organic Phosphorus	1330-78-5	2.499518	0.55	5500	0.369174	3692
Thermoplastics	Ероху	85954-11-6	50.672054	11.15	111500	7.484171	74842
Sub-Total			454.457882	100	1000000	67.122606	671226
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	2.860224	100	1000000	0.42245	4224
Sub-Total			2.860224	100	1000000	0.42245	4224
Total			677.056369			100	1000000

Important Note

The ppm calculations are at the homogeneous material level and are maximum concentration values. The ppm displayed represents the homogeneous material with the highest ppm

for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.

The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**. See Glossary of Terms for more details.

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSIs or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

For an explanation of the methods used to determine material weights, See Product Content Methodology

Material Declaration Certificate for Semiconductor IC Packaged Products

Ti certifies that the material content information provided by Ti is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. Ti semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

Tibases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. Ti may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. Ti and Ti suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by Ti. The material content information is provided by Ti "as is."

For additional information, please contact TI customer support.

Signature: (click here for a fuller statement with a signed certificate)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality For further environmental statements, please go to www.ti.com/ecoinfo Created on: 06/13/2022

RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with AGDSL and the IEC 62474 database for electronic requirements.

ROHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in http://www.ti.com/lit/pdf/szzq088

Green: Means the content of Chlorine (CI) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (5b203) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.